MA2SV03

Silicon epitaxial planar type

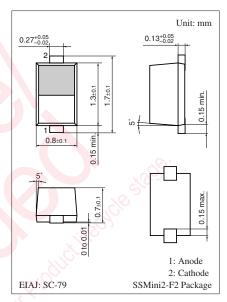
For VCO

■ Features

- \bullet Good linearity and large capacitance-ratio in $C_D V_R$ relation
- ullet Small series resistance r_D
- SS-Mini type package, allowing downsizing of equipment and automatic insertion through the taping package

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V _R	6	V
Junction temperature	Tj	150	°C
Storage temperature	T_{stg}	-55 to +150	°C



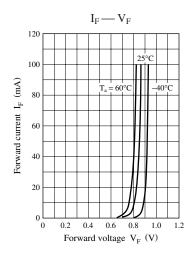
Marking Symbol: 4

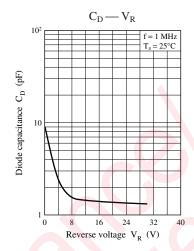
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

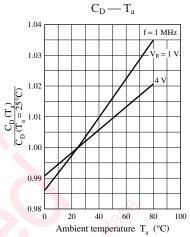
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Reverse current	I_R	$V_R = 5 \text{ V}$	100	0,	10	nA
Diode capacitance	$C_{D(1V)}$	$V_R = 1 \text{ V, f} = 1 \text{ MHz}$	5.20)-	5.80	pF
	C _{D(4V)}	$V_R = 4 \text{ V, f} = 1 \text{ MHz}$	2.10		2.58	
Capacitance ratio	C _{D(1V)} /C _{D(4V)}	618 9. 1100 100	2.1		2.6	_
Series resistance *	r_{D}	$V_R = 4 \text{ V, f} = 470 \text{ MHz}$			0.3	Ω

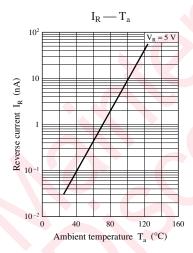
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

- 2. Absolute frequency of input and output is 470 MHz.
- 3. *: Measuring instrument; YHP MODEL 4191A RF IMPEDANCE ANALYZER









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